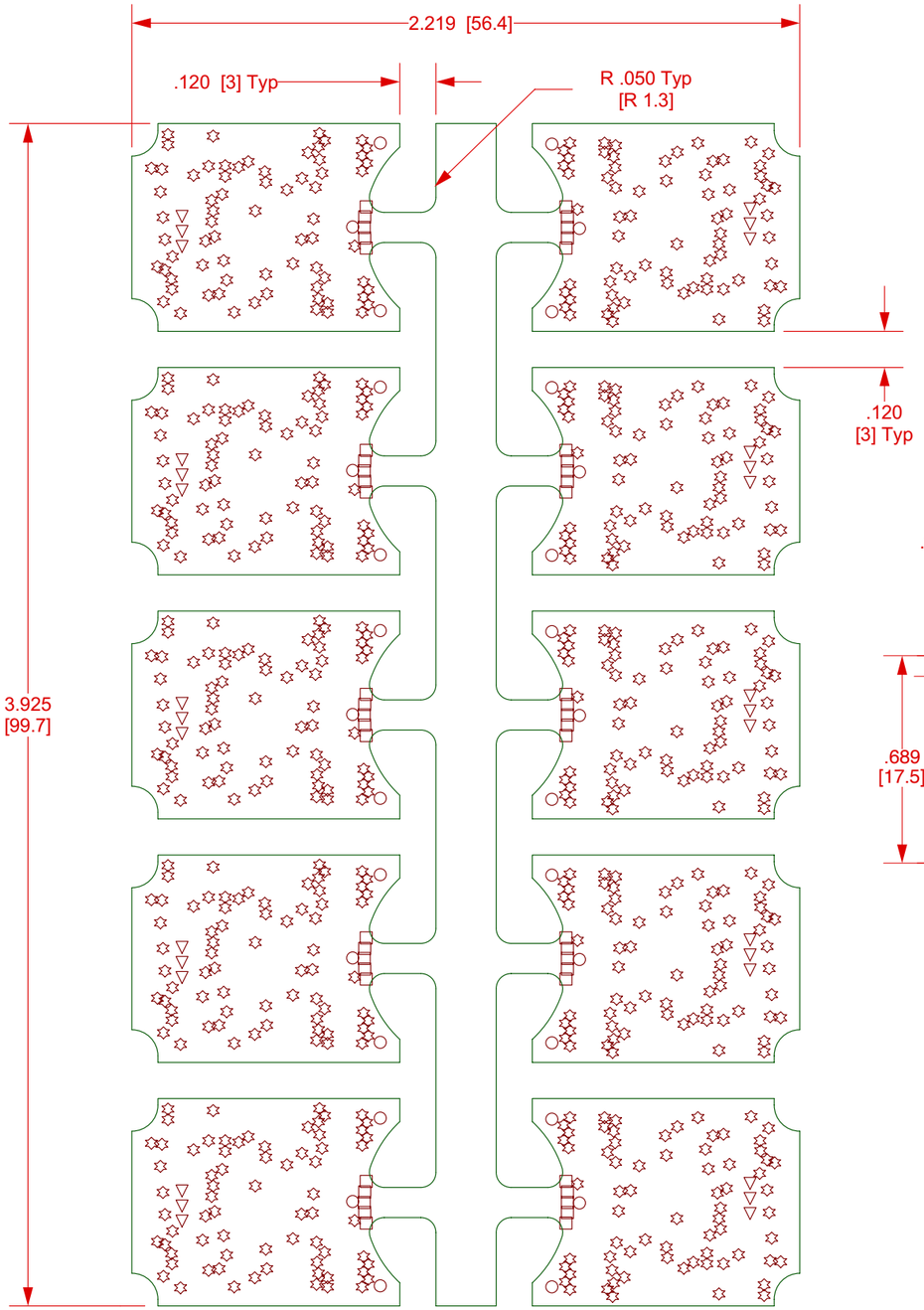
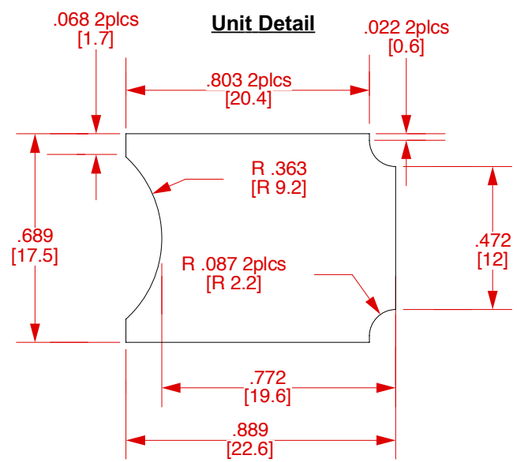




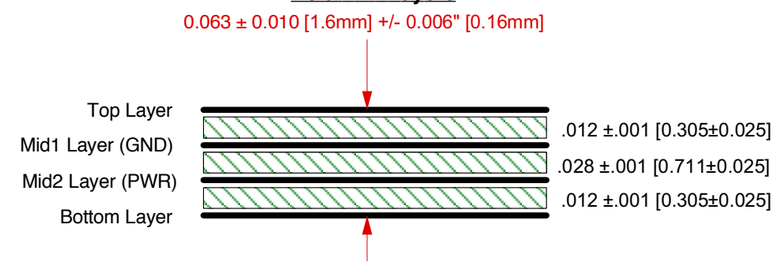
REVISION HISTORY			
REV	DESCRIPTION	DATE	APPROVED
X2	Prototype	03/20/2007	CRH
X3	Revised for MLF uP package, Hirose connector	07/19/2007	CRH

Notes:

1. Fabricate in accordance with requirements of IPC Specification #IPC-A-600C.
2. Material: Type FR4; 1 oz. Copper finished, all layers.
3. Board thickness to be 0.063"±0.010" [1.6mm] +/- 0.006" [0.16mm]
4. Coat both sides of PCB with LPI solder mask, over bare copper per IPC specification #IPC-SM-840.
5. All exposed conductor areas: HASL; SOLDER 60% TIN, 40% LEAD
7. Plating: COPPER 0.001" [0.025mm], MINIMUM; TIN/LEAD 0.003" [0.075mm]
6. Silkscreen legends over soldermask on Top and Bottom sides using non-conductive white ink. Overlap into tented holes is allowed.
7. PWB layer sequence: See Detail A
8. Finished hole tolerance: +/- 0.003" [.075], no breakout, 0.002 min. [0.05mm] annular ring.
9. Dimensions shown in Inches [Millimeters].

HOLE CHART				
Symbol	QTY.	Dia. Inches	Dia. MM	Plating
☆	700	12mil	0.305mm	PTH
▽	30	18mil	0.457mm	PTH
□	50	20mil	0.508mm	NPTH
○	30	29mil	0.737mm	PTH
TOTAL	810			

Detail A - Layers



UNLESS OTHERWISE SPECIFIED
DIM ARE IN INCHES
TOL ON ANGLE ±1/2°
1 PL ± .05 2 PL ± .02 3 PL ± .010
INTERPRET DIM AND TOL PER
ASME Y14.5M -1994

THIRD ANGLE PROJECTION

DESIGNED BY CRH 037/19/2007
DRAWN BY CRH 07/19/2007
CHECKED BY
APPROVED BY
OTHER APPROVALS
CAD FILE NAME XXX

Propeller Head Design

TITLE
OpenServo Pallet
vX3

SIZE B | CAGE CODE | DRAWING NO. | REV X3
SCALE 2X | EST. WGT | SHEET 1 of 1